

IMPACT

TE Internal #: 2057410-1

High Speed Backplane Connectors, 96 Position, Mating Alignment, Guide Slot Mating Alignment Type, 6 Row, 16 Column, PCB Mount

Receptacle, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Connector System: Board-to-Board

Number of Positions: 96

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Guide Slot

Features

Product Type Features

Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Receptacle
Shroud Style	Unshrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ground Positions	32
Number of Pairs	32
Stackable	No
Number of Signal Positions	64
Number of Positions	96
Number of Rows	6
Number of Columns	16
PCB Mount Orientation	Right Angle



Contact Mating Area Plating Material Thickness .762 µm Contact Mating Area Plating Material Gold PCB Contact Termination Area Plating Material Finish Matte		
Operating Voltage 30 VAC Signal Characteristics Number of Differential Pairs per Column 2 Data Rate 20 – 25 of Black Body Features Primary Product Color Black Contact Features PCB Contact Termination Area Plating Material Thickness 1.27 µm Contact Layout Inline Contact Type Socket Contact Underplating Material Thickness 1.27 µm Contact Mating Area Plating Material Thickness 7.62 µm Contact Mating Area Plating Material PCB Contact Termination Area Plating Material Gold PCB Contact Termination Area Plating Material Finish Matte Contact Shape & Form Dual Be		
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Contact Mating Area Plating Material Thickness .762 µm Contact Mating Area Plating Material Gold PCB Contact Termination Area Plating Material Finish Matte Contact Shape & Form Dual Be	Socket	
Contact Mating Area Plating Material Gold PCB Contact Termination Area Plating Material Finish Matte Contact Shape & Form Dual Be	1.27 μm[50 μin]	
PCB Contact Termination Area Plating Material Finish Contact Shape & Form Dual Be	.762 μm[30 μin]	
Contact Shape & Form Dual Be	Gold	
· ·	Matte	
Contact Underplating Material Nickel	Dual Beam	
	Nickel	
PCB Contact Termination Area Plating Material Tin	Tin	
Contact Base Material Copper	Copper Alloy	
Contact Current Rating (Max) .75 A	.75 A	
Termination Features		
Termination Post & Tail Length 1.2 mm	1.2 mm[.047 in]	
Termination Method to Printed Circuit Board Through	n Hole - Press-Fit	
Mechanical Attachment		
PCB Mount Alignment Type Locating	Locating Posts	
Guide Hardware With	With	
Mating Retention Without	Without	
PCB Mount Retention With	With	
PCB Mount Retention Type Action/G	Compliant Tail & Screw	
Mating Alignment With		



Mating Alignment Type	Guide Slot	
Connector Mounting Type	Board Mount	
Housing Features		
Number of Shrouded Sides	0	
End Wall Location	None	
Housing Material	LCP - GF (Liquid Crystal Polymer)	
Centerline (Pitch)	1.9 mm[.075 in]	
Dimensions		
Connector Length	38 mm[1.496 in]	
Connector Height	10.9 mm[.429 in]	
Connector Width	20.1 mm[.791 in]	
PCB Thickness (Recommended)	1.6 mm	
PCB Hole Diameter	.39 mm[.015 in]	
Row-to-Row Spacing	1.35 mm[.053 in]	
Usage Conditions		
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]	
Operation/Application		
Circuit Application	Signal	
Industry Standards		
Approved Standards	CSA Certified, UL E28476	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Method	Box & Tube, Tube	

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235)



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DOES	$\Gamma(C)$	contain	KFAU.H	$\Sigma V \square U$

· ·	gen - Br, Cl, F, I < 900 ppm per ous material. Also BFR/CFR/PVC
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Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

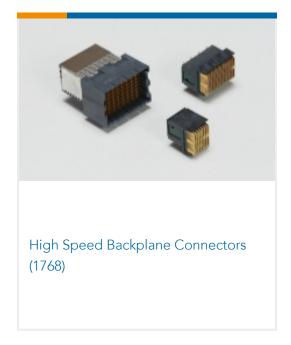
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | IMPACT



Customers Also Bought





TE Part #292336-1 Std USB Type A, Flag, T/H



TE Part #1551920-2 zQSFP+ connector assembly



TE Part #2057737-1 IMP100S,H,V2P16C,LG,OEW39,4.5



TE Part #2170790-1 CAGE ASSY, 1X4, QSFP28, SPRING, HS, LP



TE Part #2170507-5 1X3 QSFP CAGE ASSY



TE Part #2143309-3 IMP100S,H,RA2P16C,UG,OEW39,5.5



TE Part #2143313-2 IMP100S,H,RA2P16C,LG,OEW39,4.9





Documents

Product Drawings

IMP100S,R,RA2P16C,RG,39

English

CAD Files

Customer View Model

ENG_CVM_CVM_2057410-1_A.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2057410-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2057410-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages



7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

Product Specifications

Application Specification

English

Application Specification

English

Product Environmental Compliance

MD_2057410-1_05242018828_dmtec

English

MD_2057410-1_05242018828_dmtec

English

Agency Approvals

Agency Approval Document

English